SMCS Conferences and Meetings

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Steps for conference organizers to apply SMCS Technical Co-Sponsorship

Steps for applying technical co-sponsorship

Step 1: Submit all required materials through IEEE MCE portal. No manual application is allowed.
https://www.ieee.org/conference-organizers

Step 2: Preview by IEEE MCE staff.

Step 3: VP for Conferences and Meetings will receive an email notification from MCE to approve the MOU.

Step 4: After closing the conference, conference organizers need to upload presented papers to IEEE Xplore.
Steps for conference organizers to apply SMCS Financial Sponsorship

- Steps for applying financial sponsorship

Step 1: Conference organizers send a copy of budget plan to VP for Conferences and Meetings.

Step 2: After approval, VP sends it to BoG for discussion.

Step 3: After the discussion, VP sends a motion for approval by BoG.

Step 4: After approval by BoG, conference organizers submit all required materials through IEEE MCE portal. No manual application is allowed.

https://www.ieee.org/conference-organizers

Step 5: Preview by IEEE MCE staff.

Step 6: VP for Conferences and Meetings will receive an email notification from MCE to approve the MOU.

Step 7: After closing the conference, conference organizers need to upload presented papers to IEEE Xplore.
Technical Co-sponsor Fees Structure

- IEEE introduced **Technical Co-Sponsor Fees (TCS Fees)** in 2018 for all technically co-sponsored conferences in which there is no IEEE financial interest (0%). The following TCS Fee structure is currently in effect for all technically co-sponsored IEEE conferences.

- **TCS Fee Structure**
  1. US$1,450 per event
  2. US$22 for each paper submitted to IEEE Xplore®

- Technical Co-Sponsors have the option to pass this fee on to their conferences. If this occurs, the conference is responsible for paying a portion of the fee. Conferences should be mindful of this cost when budgeting for their events.
Policy of Billing for Technical Co-sponsor Fees

- Billing for technical co-sponsor fees will occur after the conference takes place.

- IEEE Systems, Man, and Cybernetics Society- (OU pays all fees for conferences $\leq 100$ papers submitted to IEEE Xplore®. Conferences pays all the fees for conferences with $101$ papers or more submitted to IEEE Xplore®.)
Long-term Plan

- **20% surplus** from the organized conferences to SMCS.

- **Industry and Students Involvement:**

  1. An email will be sent to conference organizers to remind them recruiting representatives from industry to the organizing committee, chairs, industrial sessions/tracks, student volunteers, etc.
Flagship Conferences for SMC2024~2027

- SMC 2024 in Kuching City, Malaysia
- SMC 2025 in Vienna, Austria
- SMC 2026 in Seattle, WA, USA
- SMC 2027 in Ho Chi Minh City, Vietnam
Call for SMC2028 Proposals

- Conference venue should be in Europe/Africa.
Any questions regarding organizing conferences and meetings please send emails to:

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Thank you